

AMENDMENTS

In the claims:

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20. (Canceled)
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- 32. (Canceled)
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- 35. (Previously withdrawn)
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- 45. (Previously withdrawn)
- 46. (New) A paste composition for forming a ceramic composite comprising:
 - a) at least one solvent;
 - b) at least one low-temperature frit glass; and
 - c) at least one functional particle;

wherein the paste composition is capable of being directly deposited onto a plastic substrate and wherein the at least one low-temperature frit glass has a melting point low enough that the paste composition is capable of being subsequently processed under conditions effective to provide a composite without inflicting heat related damage to the plastic substrate.

47. (New) The paste composition of Claim 46, further comprising d) at least one binder.
48. (New) The paste composition of claim 46, wherein the paste is capable of forming a "0-3 composite" ceramic element.
49. (New) The paste composition of claim 46, wherein the paste is capable of being deposited onto a substrate by a miniaturized pen.
50. (New) The paste composition of claim 46, wherein the solvent is selected from the group consisting of terpineol, dimethyl acetamide, ethylene glycol, a glyme based solvent, alkanol, butyl acetate and mixtures thereof.
51. (New) The paste composition of claim 46, wherein the low-temperature frit glass comprises lead.
52. (New) The paste composition of claim 46, wherein the at least one functional particle alters a physical property of the frit glass.
53. (New) The paste composition of claim 52, wherein the at least one functional particle raises the melting point of the frit glass.
54. (New) The paste composition of claim 46, wherein the at least one functional particle is suitable to provide a desired electronic component.
55. (New) The paste composition of claim 54, wherein the functional particle comprises a ruthenium-based resistor material, a dielectric capacitance material, or a ferromagnetic based inductor material.

56. (New) The paste composition of claim 46, wherein the at least one functional particle is selected from the group consisting of a secondary particle, molecular precursor, and a frit glass modifier.
57. (New) The paste composition of claim 46, wherein the conditions effective to provide a composite comprise a conventional low temperature processing method.
58. (New) The paste composition of claim 46, wherein the conventional low temperature processing method is a sintering method.
59. (New) The paste composition of claim 46, wherein the conditions effective to provide a composite comprise a laser processing method.
60. (New) The paste composition of claim 47, wherein the at least one binder comprises at least one sol-gel precursor.
61. (New) The paste composition of claim 60, wherein the at least one sol-gel precursor is a metal alkoxide.